

Product name FS-585 433.920000MHz 99.0 +100.-100.

Product Number / Ordering code Q25FS58500013xx

Please refer to the 5.Packing information about xx (last 2 digits)

Pb free / Complies with EU RoHS directive

Reference weight Typ. 112 mg

1.Absolute maximum ratings

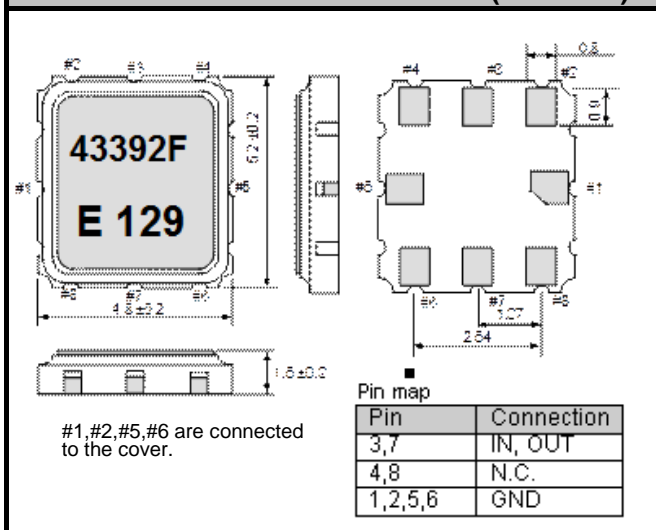
Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions / Remarks
Storage temperature	T_stg	-40	-	125	°C	-
Maximum drive level	GL	-	-	10.0	mW	Suppose to be undestroyed

2.Specifications(characteristics)

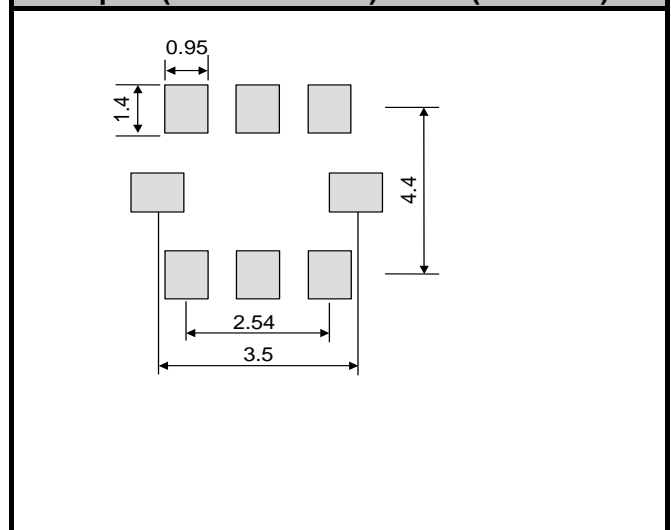
Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions / Remarks
Nominal frequency	f_nom		433.92		MHz	
Operating temperature	T_use	-40	-	120	°C	-
Level of drive	DL	-	2	-	mW	-
Frequency tolerance	f_tol	-100	-	100	$\times 10^{-6}$	-
Turnover temperature	Ti	30	40	50	°C	-
Parabolic coefficient	B	-	-3.4		$\times 10^{-8}/^{\circ}\text{C}^2$	-
Motional resistance (ESR)	R1	-	-	18	Ω	T_use= +25degC
Motional capacitance	C1	-	2.1	-	fF	315MHz
Shunt capacitance	C0	-	3.1	-	pF	315MHz
Motional inductance	L1	-	TBD	-	mH	-
Inharmonic spurious	RS/R1	R1 x 2	-	-		-
Frequency aging	f_age	-10	-	10	$\times 10^{-6} / \text{yea}$	T_use= +25degC

3.External dimensions

(Unit: mm)

**4.Footprint(Recommended)**

(Unit: mm)

**5.Packing information**

[1] Product number last 2 digits code (xx) description

The recommended code is "00"

Q25FS58500013xx

Code	Condition	Code	Condition
01	Any Q'ty vinyl bag(Tape cut)	14	1000pcs / Reel
11	Any Q'ty / Reel	15	2000pcs / Reel
12	250pcs / Reel	16	3000pcs / Reel
13	500pcs / Reel	00	4000pcs / Reel

[2] Taping specification

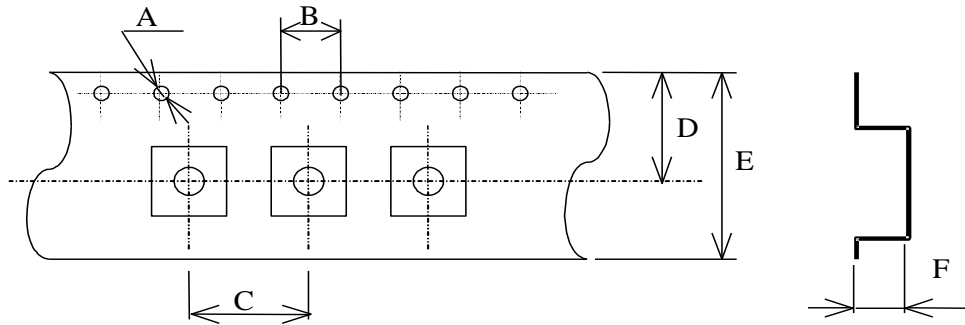
Subject to EIA-481 & IEC-60286

(1) Tape dimensions

Material of the Carrier Tape : PS

Material of the Top Tape : PET+PE

Unit: mm

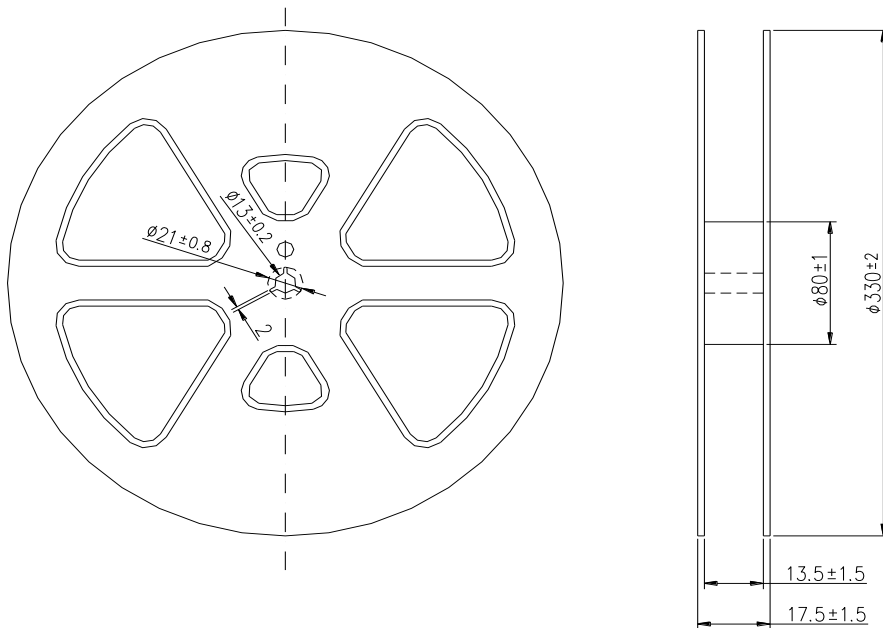


Symbol	A	B	C	D	E	F
FF-555	Φ1.5	4	8	7.25	12	1.7

(2) Reel dimensions

Material of the Reel : PS

Unit: mm



6.Reflow profile

Pre Heating Temperature

Tp1 ~ Tp2 = + 170 °C

Heating Temperature

TMI = + 220 °C

Peak Temperature

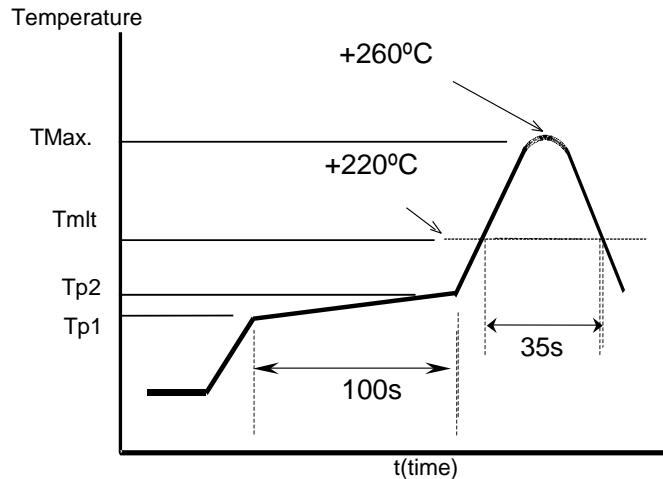
TMax. = + 260 °C

Point of measuring

In case of Solder ability

Terminal.

In case of Resistance to soldering heat
Surface.

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